

POLISHING PAD

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Abstract of JP2002198335

PROBLEM TO BE SOLVED: To provide a semiconductor wafer polishing pad for a polishing process of flattening micro unevenness of a fine pattern formed on a semiconductor wafer, which meets a need for incompatible properties of uniformity of an amount of polishing on the whole surface of the wafer and of unevenness- flattening on a minute region, and causes few scratches. **SOLUTION:** In the polishing pad used for polishing the semiconductor wafer, a polishing layer of the pad is of a porous urethane and mixed with hollow resin particles to make the layer porous, and a polishing surface-active agent of 0.05 wt. %-1 wt. % is added to the urethane resin.

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